

**PATENT APPLICATION**  
**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Kouki OGAWA, et al.

Appln. No.: 09/538,469

Confirmation No.: 6688

Filed: March 29, 2000

Docket No: Q58486

Group Art Unit: 2814

Examiner: Nathan W. Ha

For: **CAPACITOR-BUILT-IN TYPE PRINTED WIRING SUBSTRATE, PRINTED WIRING SUBSTRATE, AND CAPACITOR**

**AMENDMENT UNDER 37 C.F.R. § 1.111**

Commissioner for Patents  
Washington, D.C. 20231

Sir:

Responsive to the outstanding Office Action dated April 19, 2002, please amend the above-identified application as follows.

**IN THE CLAIMS:**

**Please enter the following amended claims:**

1. (Thrice amended) A printed wiring substrate having a planar surface and a built-in capacitor on which an IC chip is mounted, said printed wiring substrate comprising a capacitor accommodation cavity for accommodating the capacitor, characterized in that:

the capacitor comprises:

a pair of electrodes or electrode groups; and

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